

What Is Claimed Is:

- 1 1. An ESD protection component, comprising:
2 at least two MOS field effect transistors (FETs) of a first
3 conductivity type, having two gates and formed in parallel
4 on a first semiconductive layer having a second conductivity
5 type;
6 a first well having a first conductivity type, formed on
7 the first semiconductive layer, comprising:
8 a connecting area, formed between the MOS FETs;
9 two parallel extension areas, formed perpendicular to
10 the gates of the MOS FETs; and
11 a first doping area of the second conductivity type,
12 formed in the connecting area.
- 1 2. The ESD protection component in claim 1, wherein the ESD
2 protection component further comprises a guard ring of the
3 second conductivity type.
- 1 3. The ESD protection circuit in claim 2, wherein the first
2 conductive layer is connected to a power supply through the
3 guarding ring.
- 1 4. The ESD protection circuit in claim 1, wherein the first well
2 is separated from the drains of the MOS FETs.
- 1 5. The ESD protection circuit in claim 1, wherein each of the
2 MOS FETs has a source region of the first conductivity type,
3 coupled to a power rail.

1 6. The ESD protection circuit in claim 1, wherein the first well
2 is coupled to a pad through the extension areas.

1 7. The ESD protection circuit in claim 1, wherein the first
2 doping region is coupled to a pad.

1 8. The ESD protection circuit in claim 1, wherein each of the
2 MOS FETs has a drain region of the first conductivity type
3 coupled to a pad.

1 9. An ESD protection component, comprising:
2 at least two MOS field effect transistors (FETs) of a first
3 conductivity type, comprising:
4 two gates, formed in parallel on a first semiconductive
5 layer having a second conductivity type;
6 two sources of the first conductivity type, coupled to a
7 power supply; and
8 two drains of the first conductivity type;
9 a first well having a first conductivity type, formed on
10 the first semiconductive layer, comprising:
11 a connecting area, formed between the MOS FETs;
12 Two parallel extension areas, formed perpendicular to
13 the gates of the MOS FETs; and
14 a first doping area of the second conductivity type,
15 formed in the connecting area, and coupled to a pad; and
16 a guard ring of the second conductivity type, formed
17 on the first semiconductive layer, coupled to the power
18 supply;
19 wherein the first well is coupled to the pad through the
20 extension areas.